IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Slawomir RUBINSZTAJN, et al.

Title:

SOLVENT-MODIFIED RESIN SYSTEM CONTAINING FILLER THAT

HAS HIGH Tg, TRANSPARENCY AND GOOD RELIABILITY IN

WAFER LEVEL UNDERFILL APPLICATIONS

Serial No.:

To Be Assigned.
To Be Assigned.

Art Unit: Filing Date:

HEREWITH
To Be Assigned.

Examiner: Date:

September 3, 2003

INFORMATION DISCLOSURE STATEMENT

MAIL STOP PATENT APPLICATION Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Sir:

The following are submitted in the above application in compliance with 37 CFR 1.97 and 37 CFR 1.98.

[X] 1. A list of documents on Form PTO-1449 or Substitute together with copies of each identified document and a translation thereof or a concise explanation of each non-English language document or a Search Report or communication from a non-US patent office or an International Search Report from an International Searching Authority for a patent application filed via the Patent Cooperation Treaty or document(s) cited in the application or the priority application.

This paper is submitted in accordance with:

- [X] 2. 37 CFR 1.97(b): [within three months of national, non-CPA filling, prior to first Office Action, on the merits, or prior to first office action after filling an RCE]
- [] 3. 37 CFR 1.97(c): [before Final Office Action, Allowance, or other action closing prosecution, whichever is earlier]; and
 - [] a. The required Certification made in item 5 below; or

& Brew

[] b. The \$180.00 fee specified in 37 CFR 1.17(p) for submission of this Information Disclosure Statement is authorized in item 6 below.

I hereby certify that this paper or fee is being deposited with the United States Postal Service "Express Mail Post Office to Addressee" service under 37 CFR 1.10 as Express Mail No. <u>EL 985 195 715 US</u> on <u>September 3, 2003</u> and is addressed to the Mail Stop Patent Application, Commissioner for Patents, P.O. Box 1450, Alexandria, VA. 22313-1450.

Signature:

Michael R. Brew

Date: September 3, 2003

- [] 4. 37 CFR 1.97(d): [on or before issue fee payment]; and
 - a) The required Certification is stated in item 5 below; and
 - b) The \$180.00 fee specified in 37 C.F.R. 1.17(p) for submission of this Information Disclosure Statement is authorized in item 6 below.

[] 5. Certification

- [] a. Each item of information contained in this Statement was first cited in any communication from a foreign patent office in a counterpart foreign patent application not more than three months prior to the filing of this Statement; or
- [] b. No item of information contained in this Statement was cited in a communication from a foreign patent office in a counterpart foreign patent application and, to the knowledge of the person signing this document after making reasonable inquiry, no item of information contained in this Statement was known to any individual designated in 37 CFR 1.56(c) more than three (3) months prior to the filing date of this Statement.
- [] 6. Payment of all applicable fees:
 - Please charge all applicable fees associated with the submittal of this
 Information Disclosure Statement to Deposit Account No.
 - Enclosed is a check in the amount of \$_____ in payment of all applicable fees associated with the submittal of this Information Disclosure Statement.

This document is submitted in duplicate.

Respectfully submitted,

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REF/MRB/jjc

Sheet 1 of 1
Application Numbe

INFORMATION DISCLOSURE CITATION IN AN APPLICATION (Use several sheets if necessary)			Docket Number (Optional) 135371 (1306-40)		Application Number To Be Assigned		
			Applicant Slawomir RUBINSZTAJN, et al.				
			Filing Date HEREWITH		Group Art Number To Be Assigned		
		U.S. PATEN	T DOCUMENTS				
Examiner Initial	Document Number	Date	Name	Class	Subclass	Filing Da if Approp	
	6,576,718	6/10/2003	Yeager et al.				
	6,555,602	4/29/2003	Harada et al.				
	6,548,189	4/15/2003	Gunasekaran et al.	<u> </u>			
	6,486,235	11/26/2002	Cooray et al.			 	
	4,217,438	8/12/1980	Brunelle et al.			 	
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		FOREIGN PAT	ENT DOCUMENTS				
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	 	OTHER D	OCUMENTS				
}			p-Chip Applications," 2003	B Electroni	c Compone	ents and	
	Technology Conference	, pages 951-956.	ance No-Flow Underfill," 2	002 Intern	ational Syr	nnosium o	
	Microelectronics, pages		ance NO-HOW Officerist, 2	OUZ IIIIGIII		iposiulli Ol	'
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